

REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

A

B

C

D

E

F

A

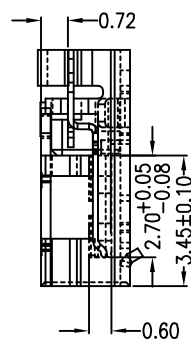
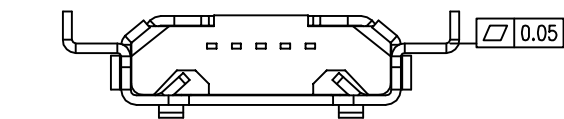
B

C

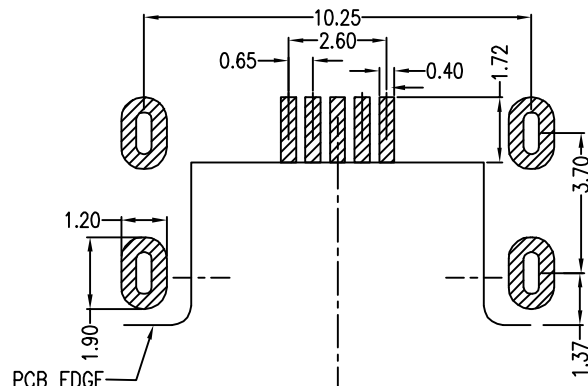
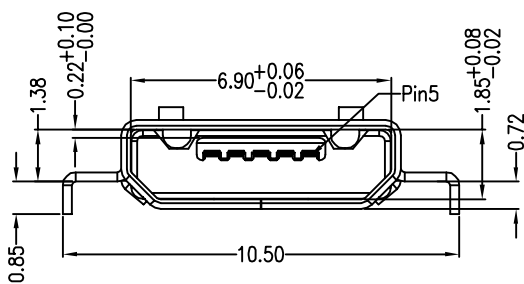
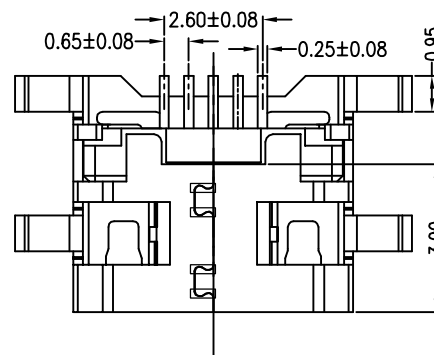
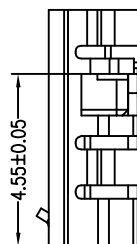
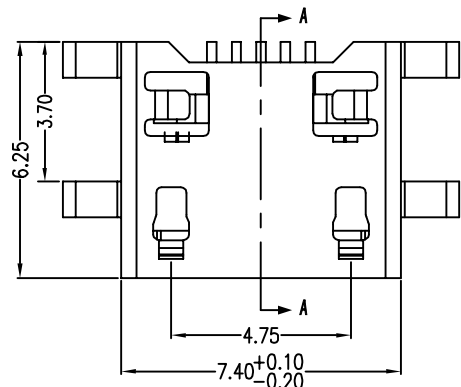
D

E

F



SEC A-A



RECOMMENDED PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

A 01 S B 1 4 1 B 3-259

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

- | | |
|--------------------------|--|
| ① 产品代号 A:成品 | ⑥ 端子材质 4:C5191R-EH |
| ② 产品系列 01:micro usb 5pin | ⑦ 主体材质 1:LCP |
| ③ 产品类别 S:母座 | ⑧ 主体颜色 B:黑色 |
| ④ 产品类型 B:B TYPE | ⑨ 下板类型 3:沉板式 |
| ⑤ 外壳材质 1:C2680R-H | ⑩ 细节流水 259:Micro usb 5s B Type Smt沉板式无导位无接地片 |

PART NO: AO1SB141B3-259		MATERIAL: SEE NOTE	
MODEL NO: XX		FINISH: SEE NOTE	
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED		DR: 夏友红	
.x	0.25	CHK:	
.xx	0.20	APP:	
.xxx	0.15	SCALE: 5:1	
Ang.	2'	DATE: 2012.06.18	
TITLE: Micro usb 5s B Type Smt沉板式无导位无接地片		REV: A	
DWG NO: A259		DATE: 2012.06.18	

